

Artificially atomically engineered materials for storage and cognitive computing applications

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San Jose, California**

- Complex, multi-functional materials for emerging devices
 1. Beyond silicon: cognitive devices for low power computing
 2. Spintronic devices: novel phenomena involving electron spin currents
 3. 3D devices: e.g. Racetrack Memory – a current controlled shift register
- Requires combination of deep understanding, advanced theoretical models, computational exploration & analytics and experimental verification
- Useful devices require materials optimized for many distinct properties

Evolution in World's Compute Capacity

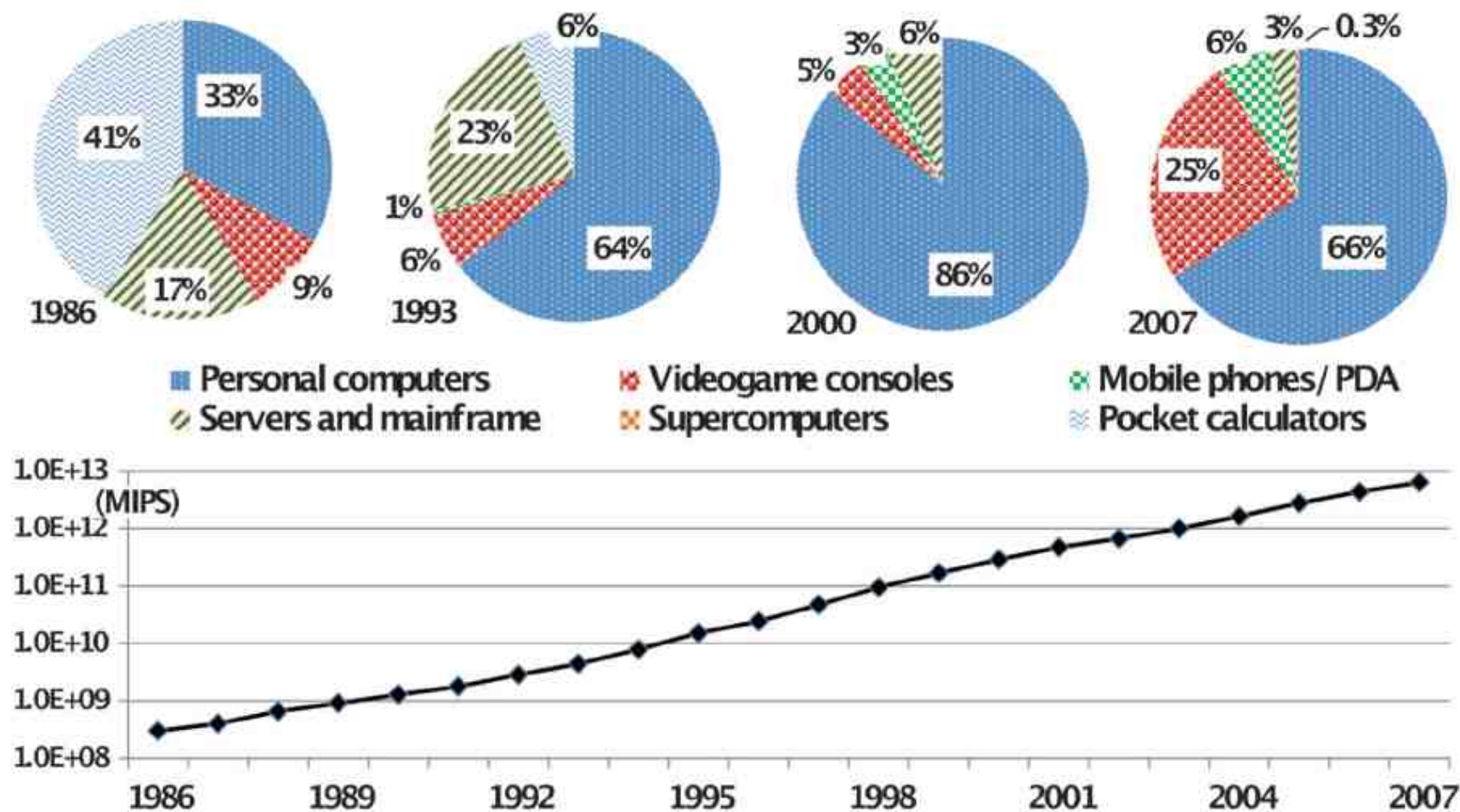


Fig. 5. World's technological installed capacity to compute information on general-purpose computers, in MIPS (table SA3) (16).
Hilbert et al. Science (2011)

“Volume. As of 2012, about 2.5 exabytes of data are created each day, and that number is doubling every 40 months or so. More data cross the internet every second than were stored in the entire internet just 20 years ago. This gives companies an opportunity to work with many petabytes of data in a single data set—and not just from the internet. For instance, it is estimated that Walmart collects more than 2.5 petabytes of data every hour from its customer transactions. A petabyte is one quadrillion bytes, or the equivalent of about 20 million filing cabinets’ worth of text. An exabyte is 1,000 times that amount, or one billion gigabytes.”

*“Big Data: The Management Revolution”, McAfee and
Brynjolfsson, Harvard Business Review, October 2012*

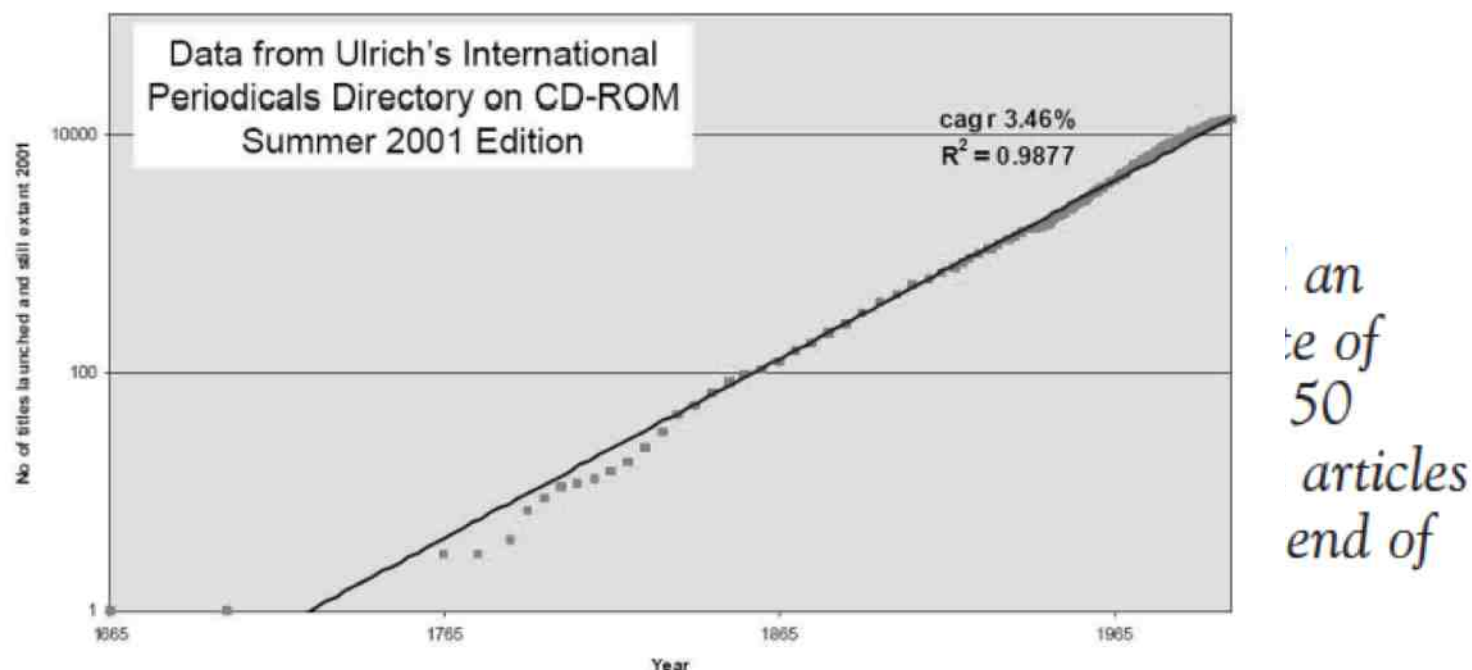


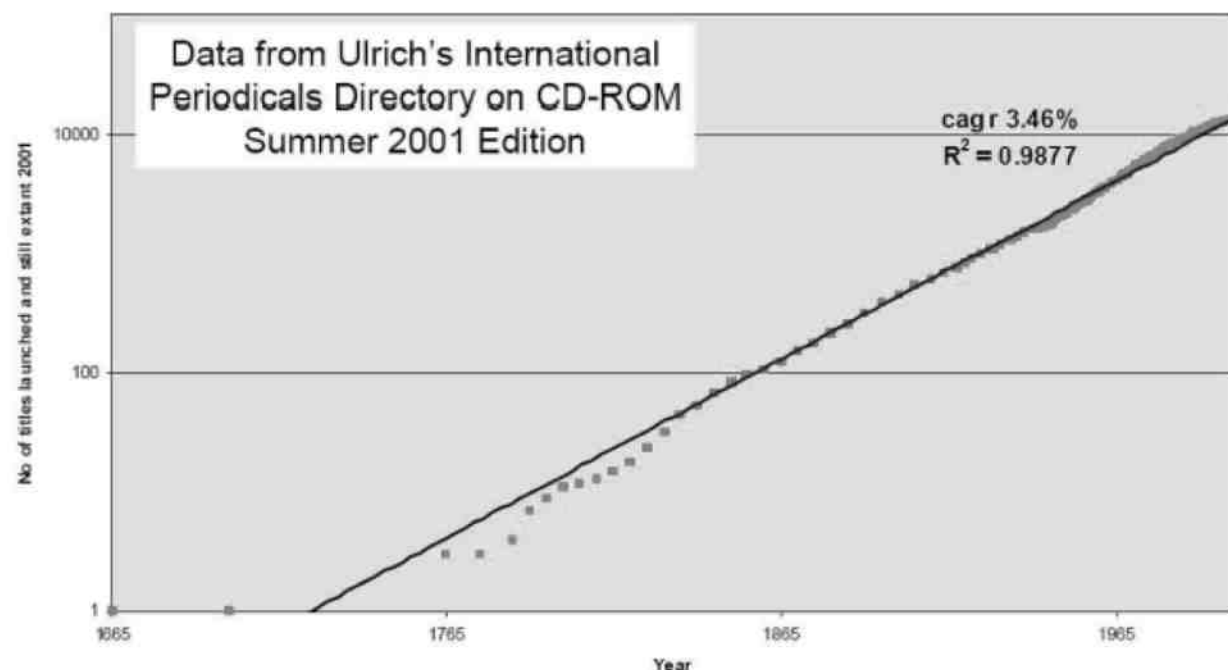
Figure 1. Number of journals launched per year

Source: *Ulrich's International Periodicals Directory*, reproduced with permission from Mabe.³

Year Jinha, A. E. *Learned Publishing* **2010**, 23, 258-263.

Figure 2. Estimated annual global research article output at 3% annual growth

*Year 1985 (2009 – 25 years): the doubling time for annual output for articles of just under 24 years; **1999: corresponds to estimates by Tenopir and King,⁶ for research output in the late 1990s – 1 million articles per year; ***2006: corresponds very closely to Björk *et al.*'s,² estimate for 2006 – 1.35 million articles; ****2007: corresponds closely to Ware's,⁴ estimate for the same period – 1.4 million articles per year.



an
e of
50
articles
end of

Figure 1. Number of journals launched per year

Source: Ulrich's International Periodicals Directory, reproduced with permission from Mabe.³

Most data is "locked"

→ In thousands of distinct journals

→ Not in open source journals

→ Not in searchable formats e.g. figures and tables

→ Similarly, difficult to extract useful data from patent literature

Figure 2. Estimated annual global research article output at 3% annual growth

*Year 1985 (2009 – 25 years): the doubling time for annual output for articles of just under 24 years; **1999: corresponds to estimates by Tenopir and King, for research output in the late 1990s – 1 million articles per year; ***2006: corresponds to estimates by Tenopir and King, for research output in the late 1990s – 1 million articles per year; ****2007: corresponds closely to War's 4 estimate for the same period – 1.4 million articles per year.

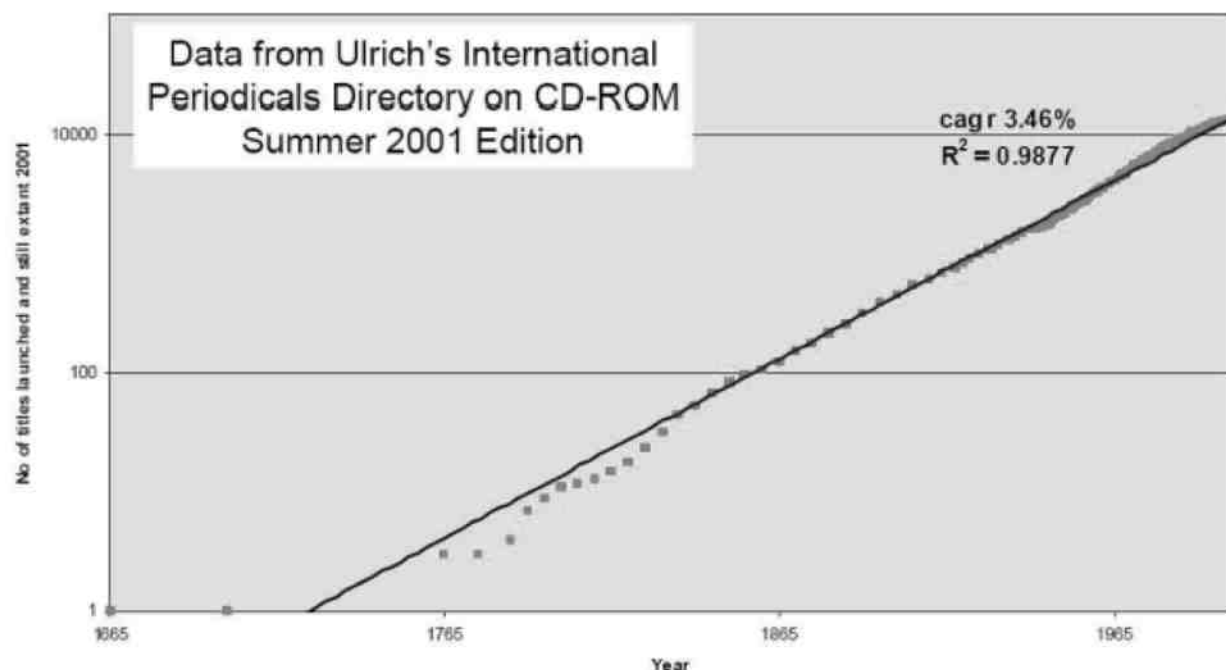


Figure 1. Number of journals launched per year

Source: *Ulrich's International Periodicals Directory*, reproduced with permission from Mabe.³

MGI: provide access to materials data

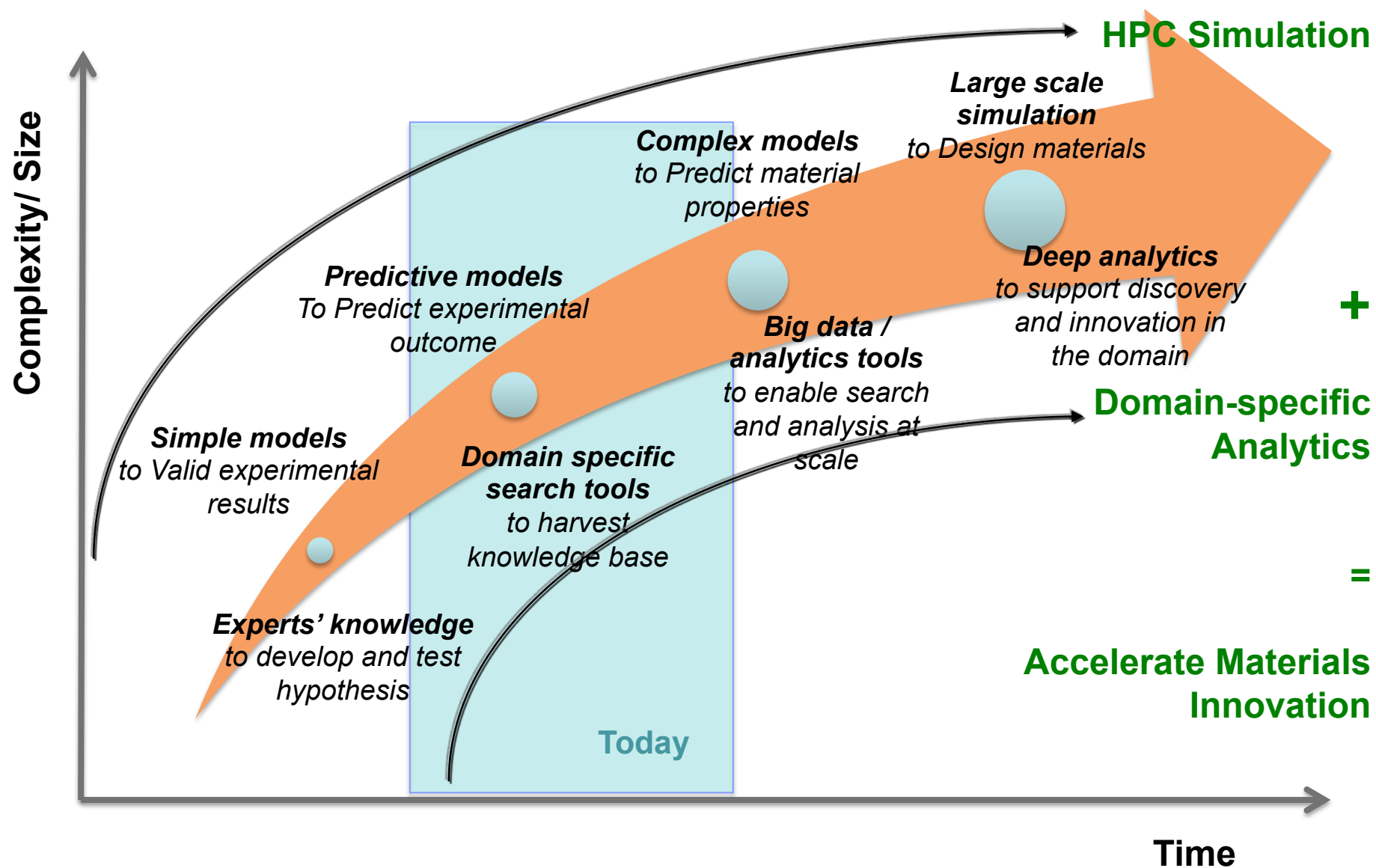
Jinha, A. E. *Learned Publishing* **2010**, 23, 258-263.

→ via a “MGI” social network

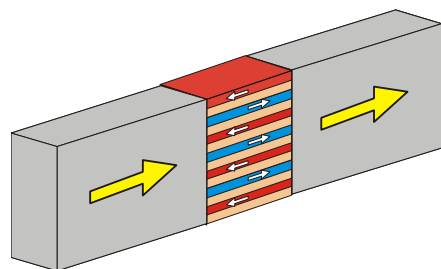
→ Need to “map” the Materials Genome with the help of all scientists

→ Need access to failures as well as successes!

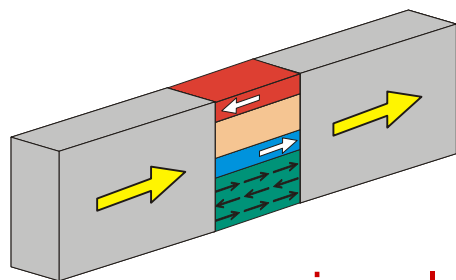
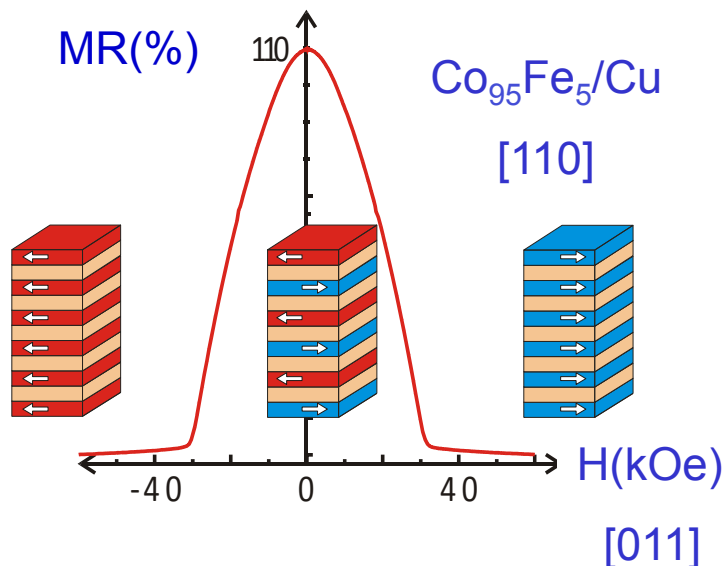
→ experiments that failed are just as important as those that worked



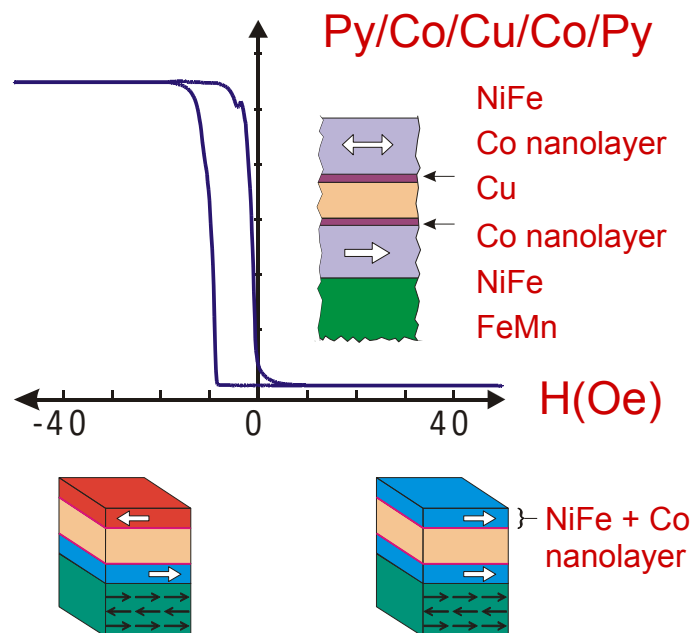
Giant Magnetoresistance (GMR)



multi-layer
 $\Delta R/R \sim 110\%$ at RT
 Field $\sim 10,000$ Oe



spin-valve
 $\Delta R/R \sim 8-17\%$ at RT
 Field ~ 1 Oe



GMR

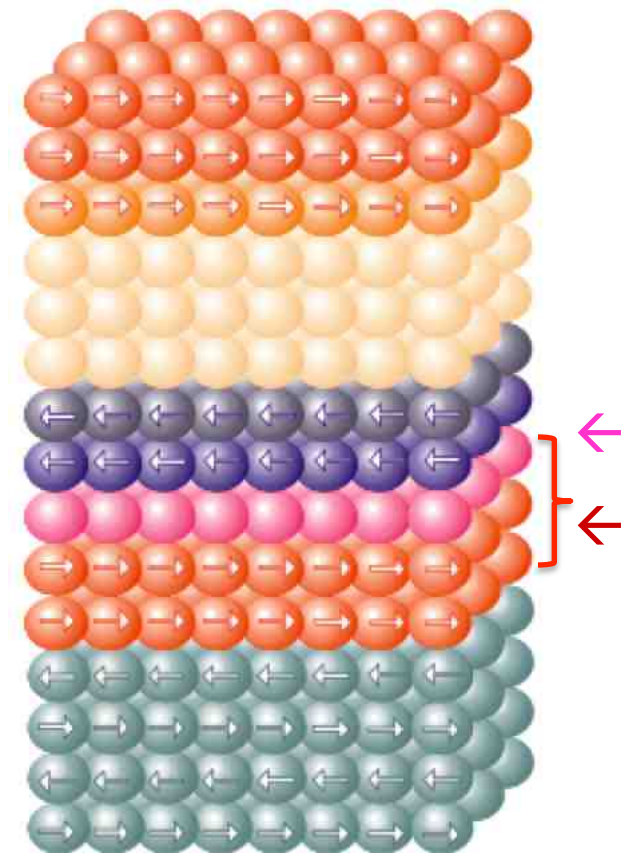
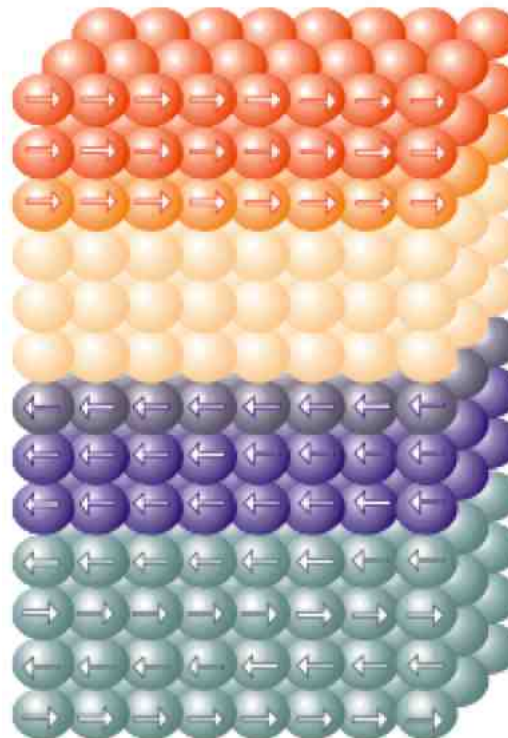
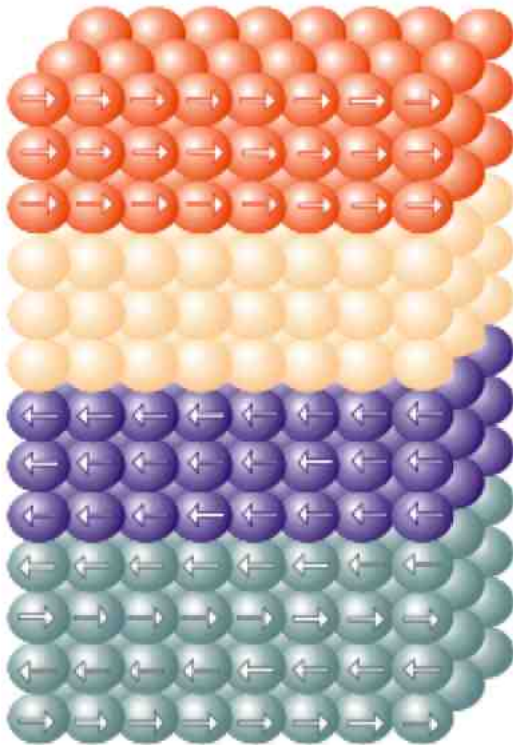
- metallic spacer between magnetic layers
- current flows in-plane of layers

S.S.P. Parkin, in *Ultrathin Magnetic Structures*, edited by B. Heinrich and J.A.C. Bland (Springer-Verlag, Berlin, 1994), Vol. II, pp. 148.

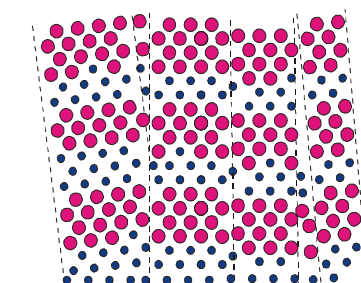
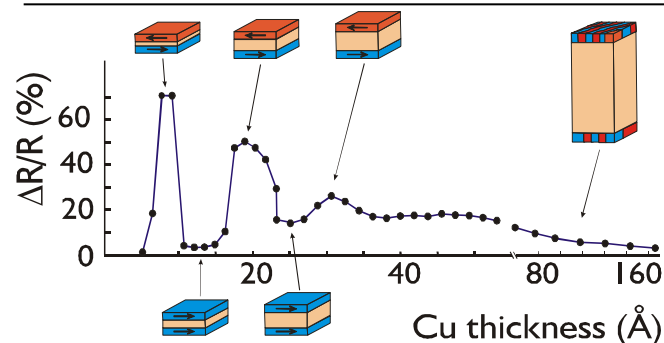
Spin-valve
GMR sensor

+ interface
engineering to
optimize transport

+ Artificial
Antiferromagnet to
engineer magnetics



Oscillatory Giant Magnetoresistance (GMR)



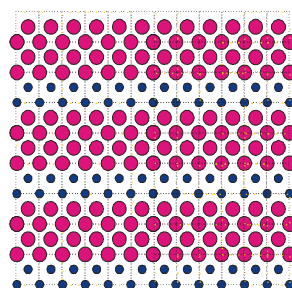
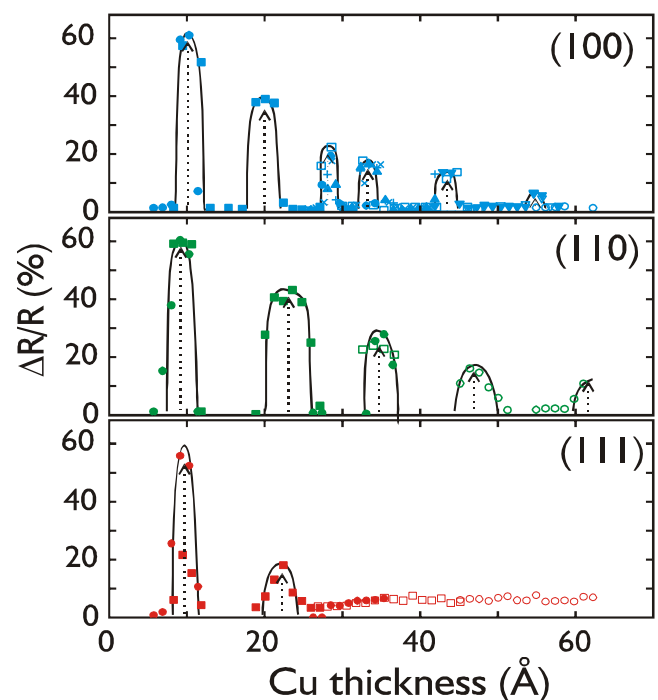
Polycrystalline

→ oscillatory interlayer coupling mediated by atomically thin Cu layers

→ Peaks in GMR when AF coupling via Cu layer

→ oscillation periods ranging from 5 to 12 Å

→ oscillation periods could be foreseen from Fermi surface topology



Single crystalline

Parkin et al, Phys. Rev. Lett. 66, 2152 (1991)

Periodic Table of Oscillatory Exchange Coupling Strengths



ELEMENT

A_1 (A)	ΔA_1 (A)
J_1 (erg/cm ²)	P (A)

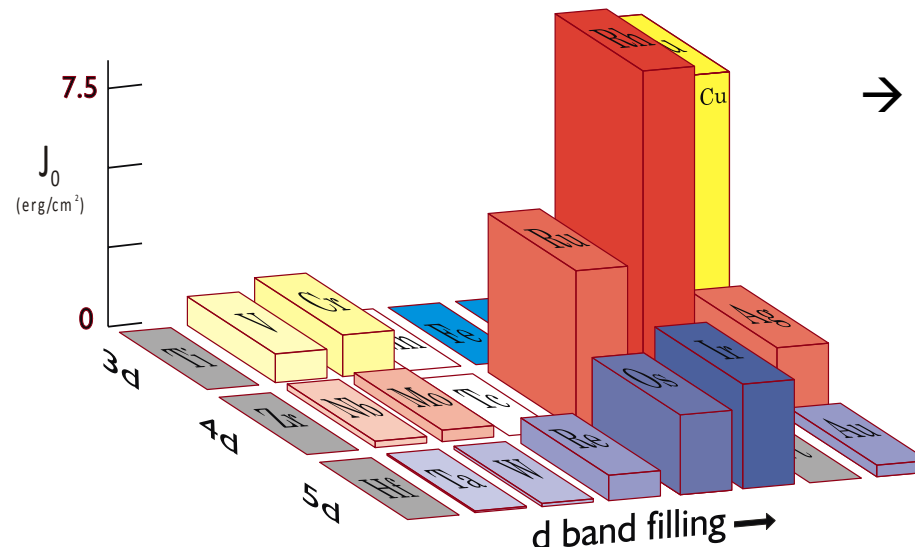
fcc
 bcc
 hcp
 complex cubic

Ti	V	Cr	Mn	Fe	Co	Ni	Cu
No COUPLING	9 0.1	3 9	7 .24	7 18	FERRO-MAGNET	FERRO-MAGNET	FERRO-MAGNET
							8 0.3
Zr	Nb	Mo	Tc	Ru	Rh	Pd	Ag
No COUPLING	9.5 .02	2.5 *	5.2 .12	3 11	3 5	7.9 1.6	3 9
						FERRO-MAGNETIC COUPLING	
Hf	Ta	W	Re	Os	Ir	Pt	Au
No COUPLING	.01 *	2 *	5.5 .03	3 *	4.2 .41	3.5 10	4 1.85
						FERRO-MAGNETIC COUPLING	9

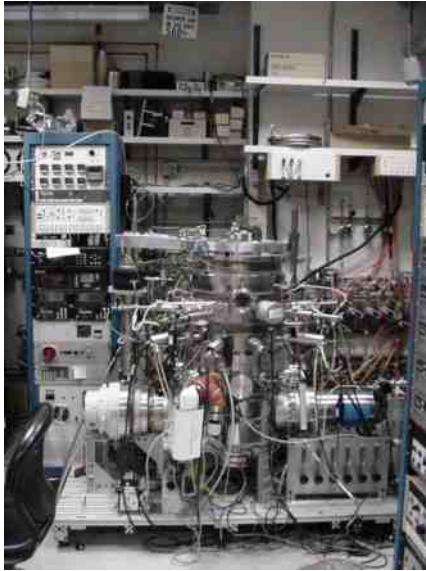
- Strength of interlayer coupling could not be predicted without a detailed understanding of underlying physics

- Interfacial property

→ Analytical models are very important!



Parkin, Phys. Rev. Lett. 67, 3598 (1991)



1992-1995: S-System

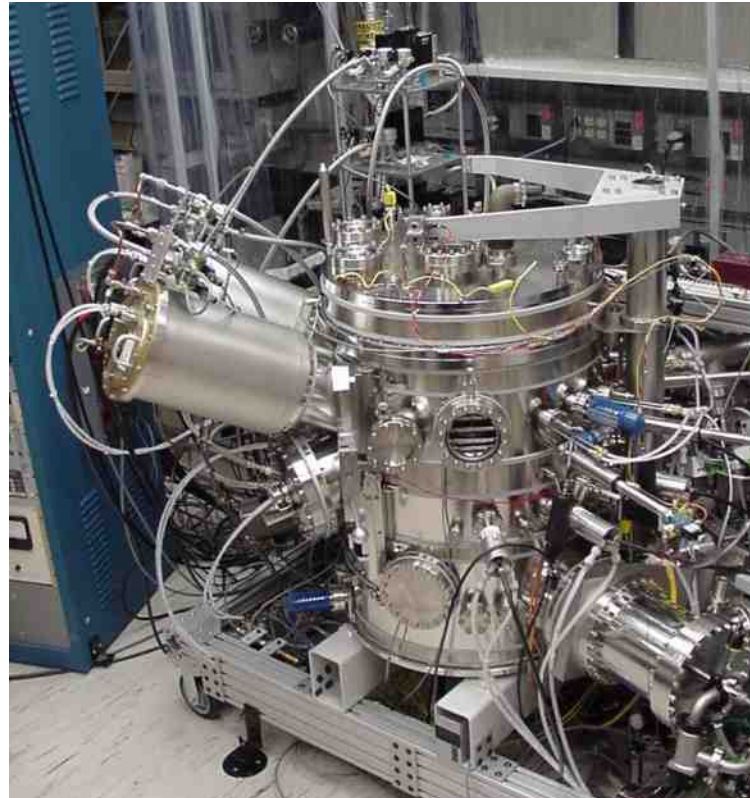
6 magnetron sources

1 oxidation source

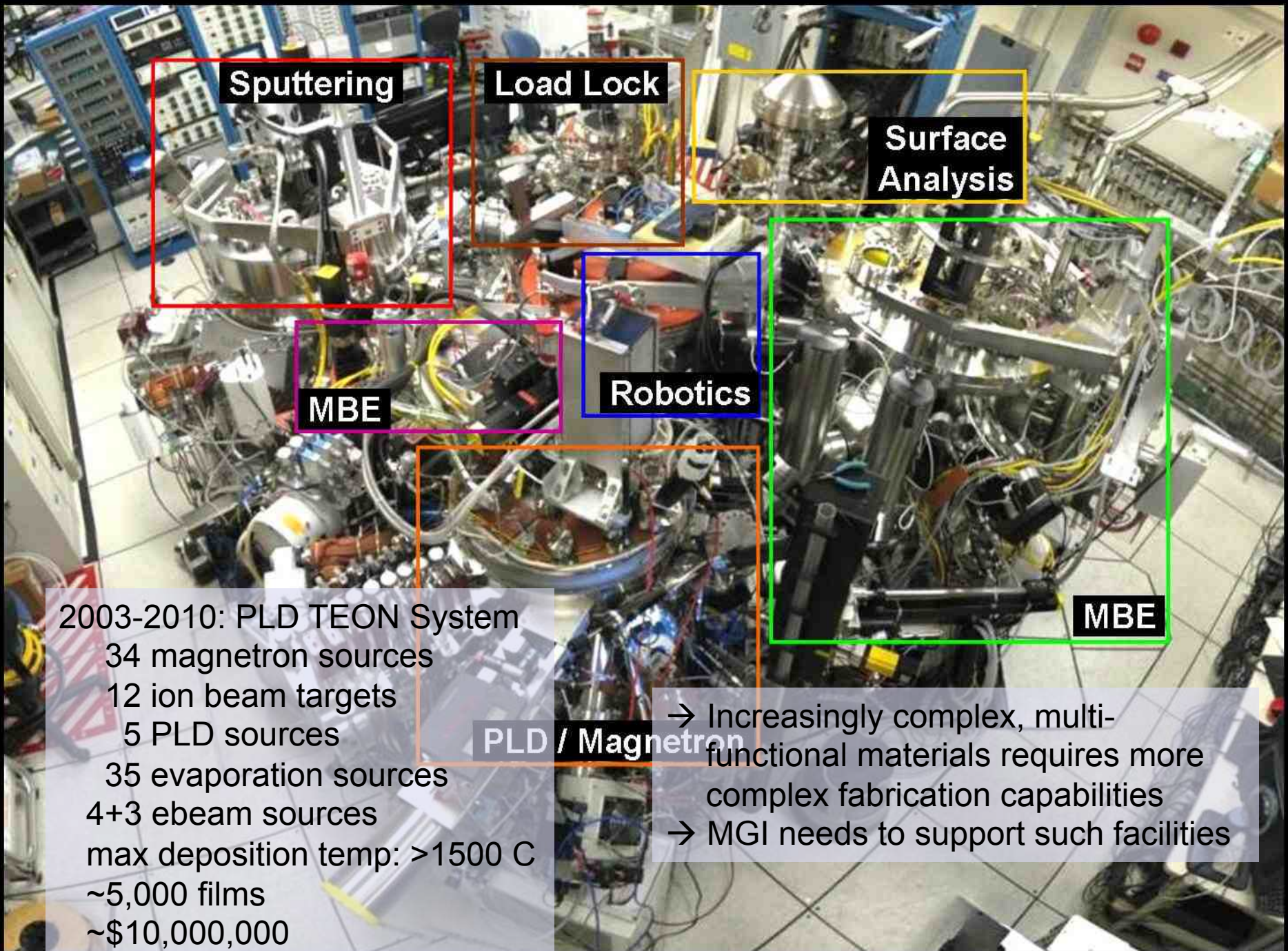
max deposition temp: 550 C

~82,000 films

~\$100,000



1997-1999: A system
9 magnetron sources
5 ion beam sputter targets
max deposition temperature: 550 C
~52,000 films
~\$400,000



2003-2010: PLD TEON System
34 magnetron sources
12 ion beam targets
5 PLD sources
35 evaporation sources
4+3 ebeam sources
max deposition temp: >1500 C
~5,000 films
~\$10,000,000

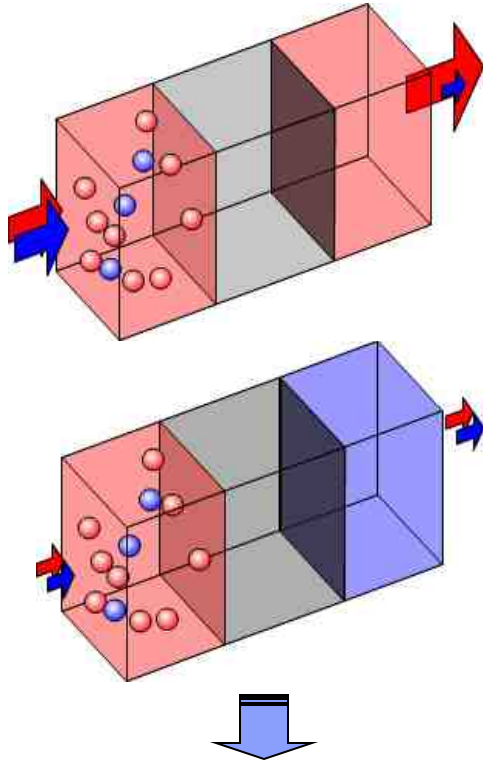
PLD / Magnetron

→ Increasingly complex, multi-functional materials requires more complex fabrication capabilities
→ MGI needs to support such facilities

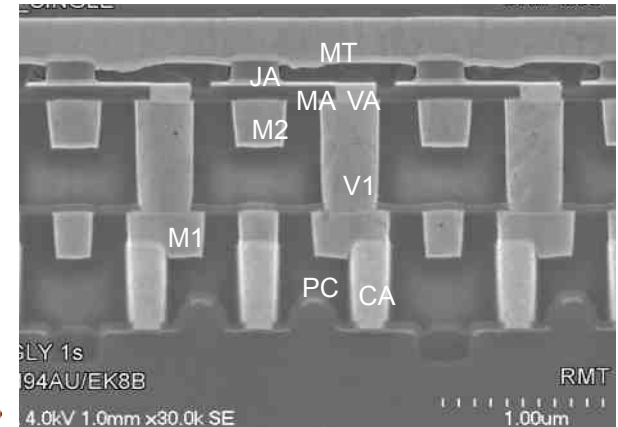
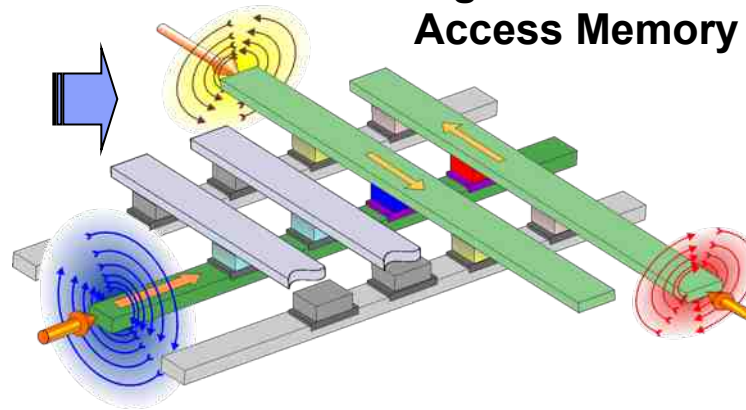
Magnetic Memory & Storage



Magnetic Tunnel



Magnetic Random Access Memory



IBM-IFX 16Mbit MRAM

Fast reading and writing

→ High performance

→ Good endurance

→ High cost

New materials for MTJ needed

→ Extant materials (CoFeB/MgO) suitable to ~30 nm node

→ Need materials with higher magnetic anisotropy for 10 nm node

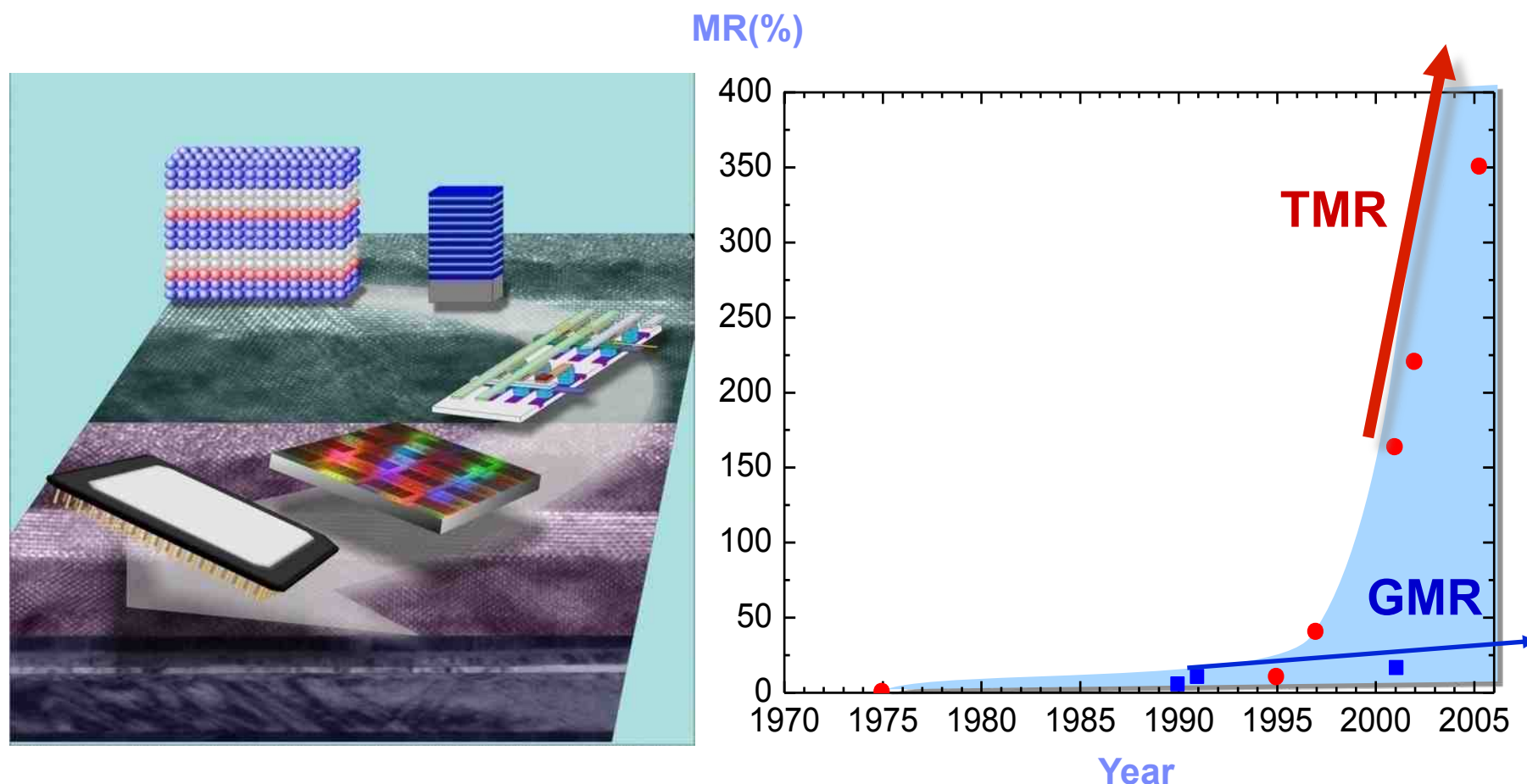
Read Heads – Disk Drives



Massive storage capacity

→ Very cheap

→ But slow and unreliable!



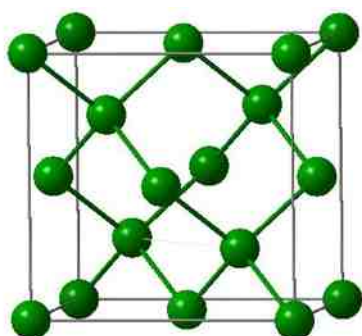
→ Huge room temperature TMR values in MTJs useful for memory and sensing applications using CoFe(B) / MgO
~220% in 2001-2002: → 400-600% today!

[*Parkin et al. Nature Mater. (2004)*; *Yuasa et al. Nature Mater. (2004)*]

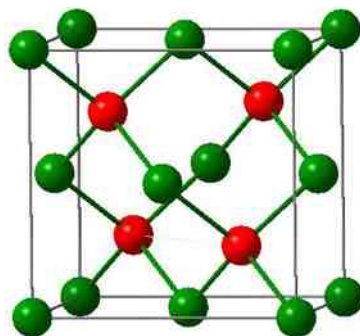
Heusler Compounds



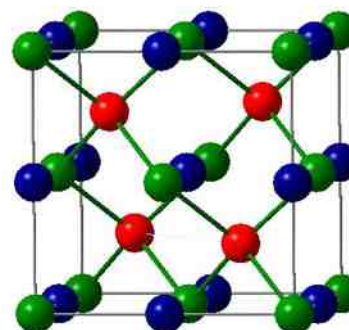
Diamond



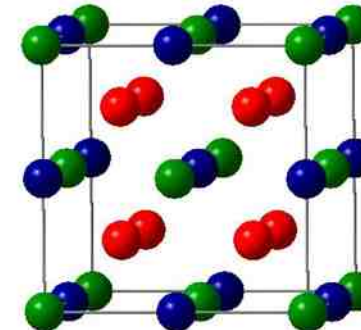
ZnS



Heusler XYZ C1_b



X₂YZ L2₁



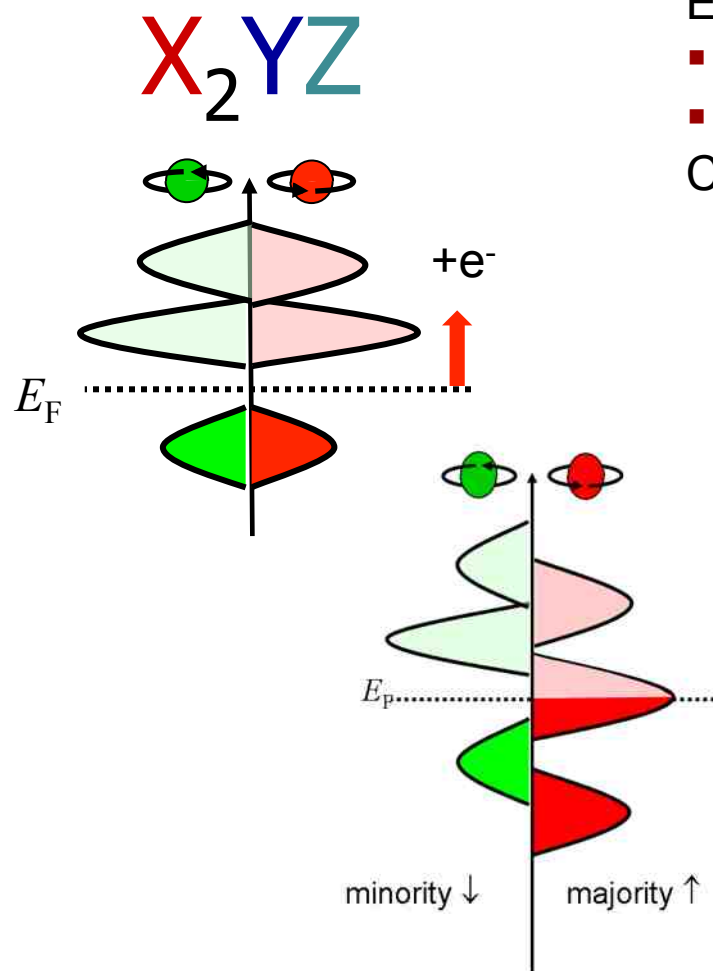
C 2.55	N 3.04
Si 1.90	P 2.19
Ge 2.01	As 2.18
Sn 1.96	Sb 2.05

H 2.20																	He				
Li 0.98	Be 1.57															B 2.04	C 2.55	N 3.04	O 3.44	F 3.98	Ne
Na 0.93	Mg 1.31															Al 1.61	Si 1.90	P 2.19	S 2.58	Cl 3.16	Ar
K 0.82	Ca 1.00	Sc 1.36	Ti 1.54	V 1.63	Cr 1.66	Mn 1.55	Fe 1.83	Co 1.88	Ni 1.91	Cu 1.90	Zn 1.65	Ga 1.81	Ge 2.01	As 2.18	Se 2.55	Br 2.96	Kr 3.00				
Rb 0.82	Sr 0.95	Y 1.22	Zr 1.33	Nb 1.60	Mo 2.16	Tc 1.90	Ru 2.20	Rh 2.28	Pd 2.20	Ag 1.93	Cd 1.69	In 1.78	Sn 1.96	Sb 2.05	Te 2.10	I 2.66	Xe 2.60				
Cs 0.79	Ba 0.89		Hf 1.30	Ta 1.50	W 1.70	Re 1.90	Os 2.20	Ir 2.20	Pt 2.20	Au 2.40	Hg 1.90	Tl 1.80	Pb 1.80	Bi 1.90	Po 2.00	At 2.20	Rn				
Fr 0.70	Ra 0.90																				
		La 1.10	Ce 1.12	Pr 1.13	Nd 1.14	Pm 1.13	Sm 1.17	Eu 1.20	Gd 1.20	Tb 1.10	Dy 1.22	Ho 1.23	Er 1.24	Tm 1.25	Yb 1.10	Lu 1.27					
		Ac 1.10	Th 1.30	Pa 1.50	U 1.70	Np 1.30	Pu 1.28	Am 1.13	Cm 1.28	Bk 1.30	Cf 1.30	Es 1.30	Fm 1.30	Md 1.30	No 1.30	Lr 1.30					

7 (2011)
9, 1 (2011)

Graf, Felser, and Parkin, IEEE Trans. Magn. **47**, 367 (2011)
 Graf, Felser, and Parkin, Prog. Solid State Chem. **39**, 1 (2011)

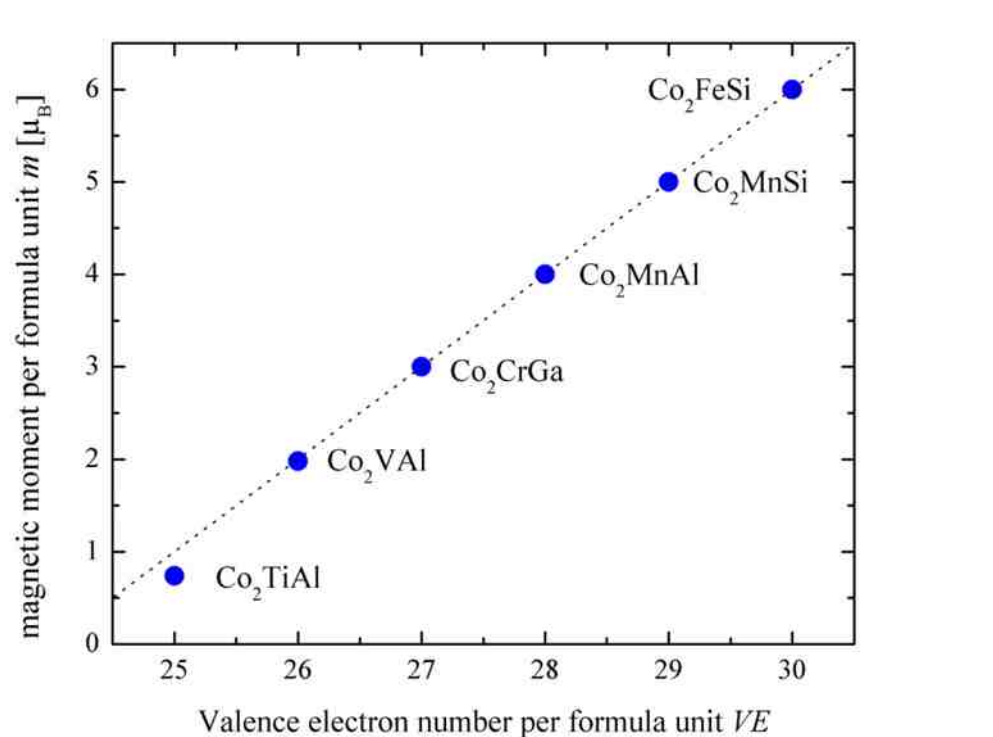
Heusler compounds → Half-metallic ferromagnets



Example: Co_2MnSi

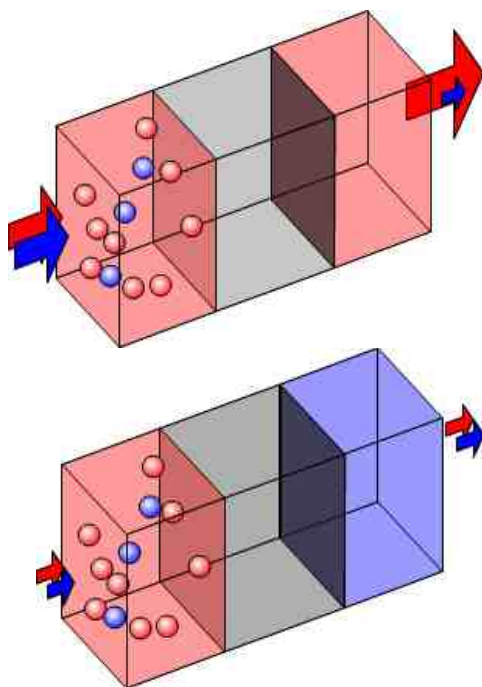
- magic valence electron number: 24
- valence electrons = 24 + magnetic moments

$$\text{Co}_2\text{MnSi}: 2 \times 9 + 7 + 4 = 29 \quad M_s = 5\mu_B$$



Kübler *et al.*, PRB **28**, 1745 (1983)

Galanakis *et al.*, PRB **66**, 012406 (2002)



$$J \approx 1 - 100 \text{ MA/cm}^2$$

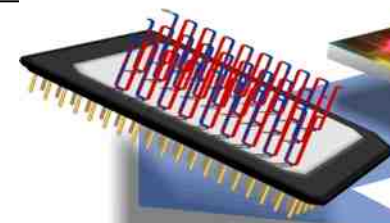
$$J \approx \frac{e}{\hbar g} \alpha M_s H_U d$$

Shopping list for STT devices

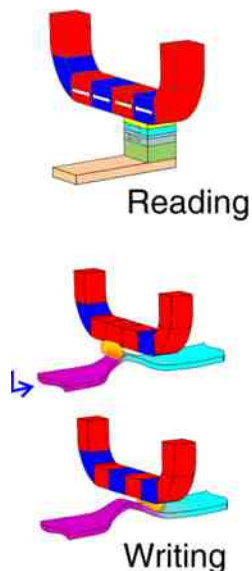
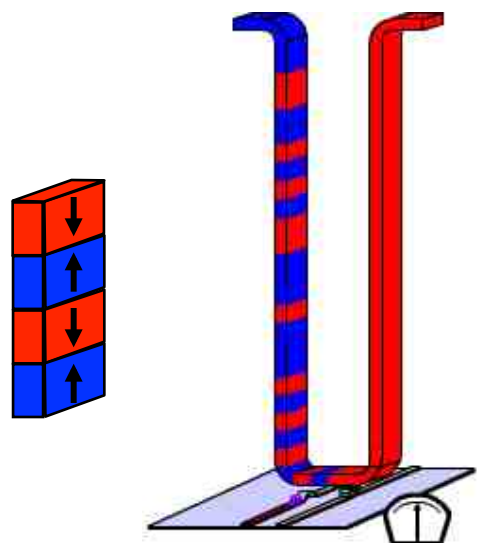
Switching by current

- High spin polarization
- High Curie temperature, T_C
- low magnetic damping
- low saturation magnetization
- high perpendicular anisotropy

Magnetic Racetrack Memory



Vertical Racetrack

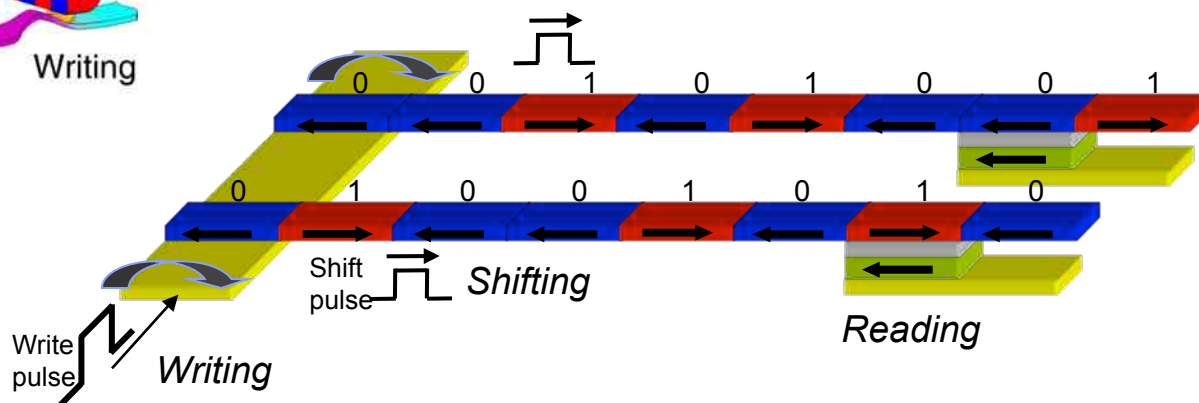


- Bits = Domains in the tracks

- A novel three-dimensional storage class memory

- The capacity of a hard disk drive

Horizontal Racetrack



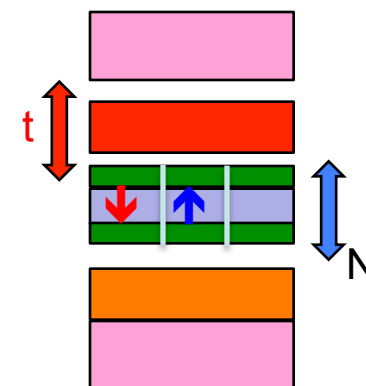
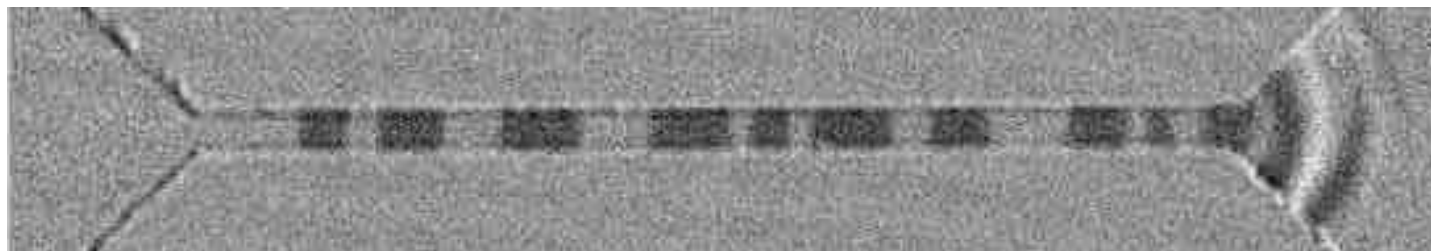
- The capacity of a FLASH

Parkin, US patents 6834005, 6898132

Parkin et al., Science 320, 190 (2008)

Parkin, Scientific American (2009)

Racetrack Memory 2.0



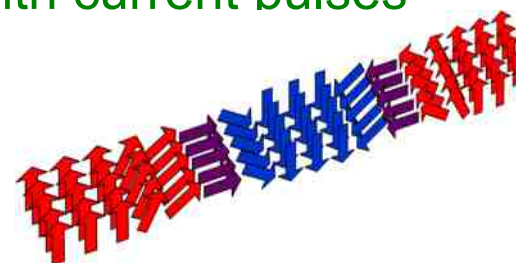
→ 20 domain walls moved in lock step with current pulses

→ High velocity at low current density

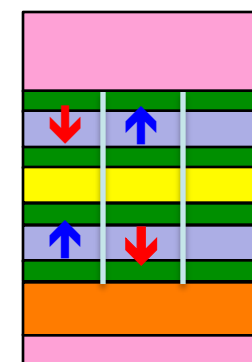
→ Narrow domain walls

→ Very thin racetracks

– writing domain walls possible with SHE, Rashba, STT



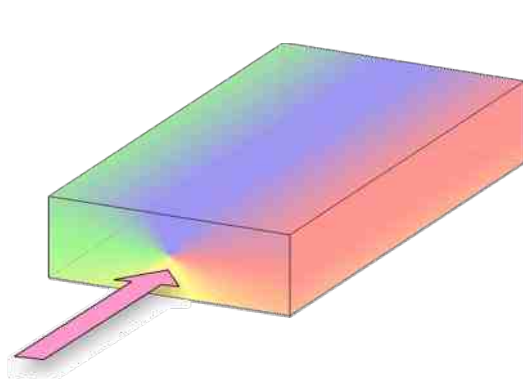
→ Remaining problem: magnetostatic coupling between domain walls solved by using a “synthetic antiferromagnet (SAF)”



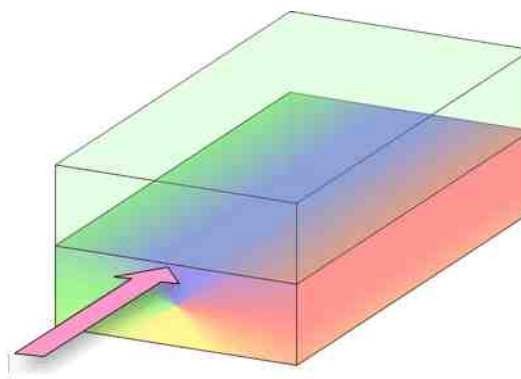
Spin Hall Effect: due to spin orbit coupling from Pt



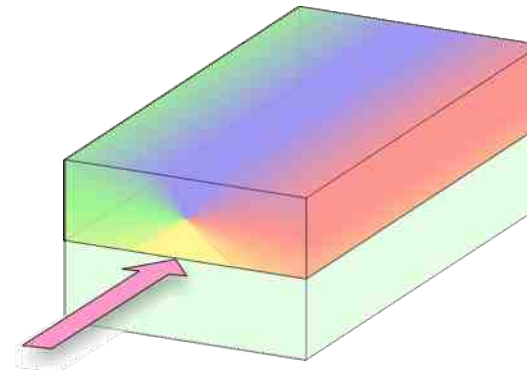
- Spin orbit coupling effect from current flowing in Pt layer leads to Spin Hall Effect



When current flows,
spin accumulates on
the edges and surfaces
of the Pt layer



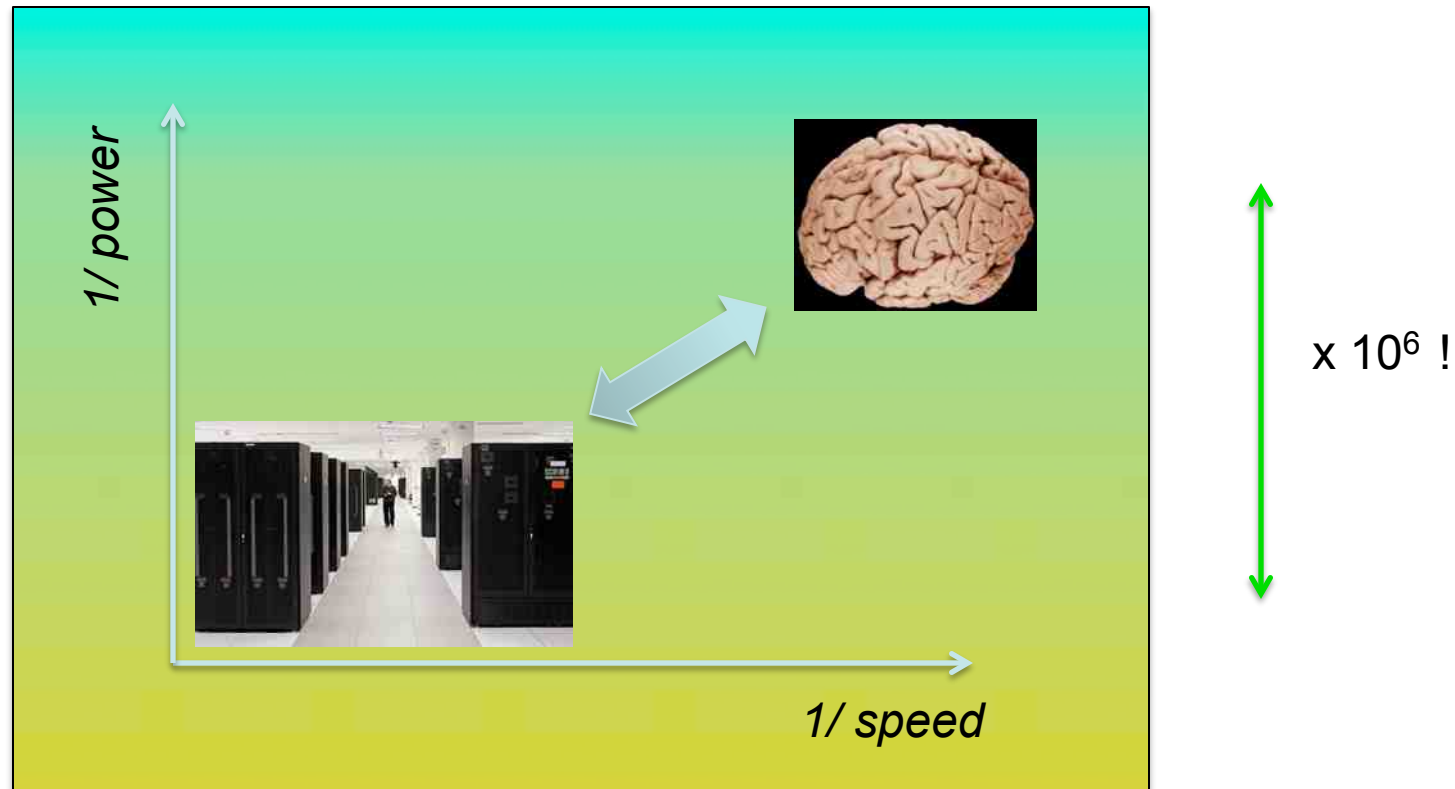
Spin polarization in Pt
induces torque on
adjacent Co layer



Effect on adjacent
layers depends on
Pt-Co order

- Magnitude of SHE has both intrinsic and extrinsic origins
- MGI very important to quickly identify materials with large SHE
 - Use of Inverse SHE could lead to novel cheap energy harvesting devices (Saitoh/NEC)

Silicon versus biology!



→ 10^6 performance/ energy gap between CMOS and biology!

Computers and the Brain are Dramatically Different



Separates memory and processor

Sequential, centralized processing

Ever increasing clock rates, high active power

Huge passive power

Programmed system, hard-wired, fault-prone

Algorithms and analytics



Integrates memory and processor

Parallel, distributed processing

Event-driven, low active power

Does “nothing” better, low passive power

Learning system, reconfigurable, fault-tolerant

Substrate and pattern recognition

Tuning the electronic properties of complex oxides



Charge carrier modulation by electric field effect gating

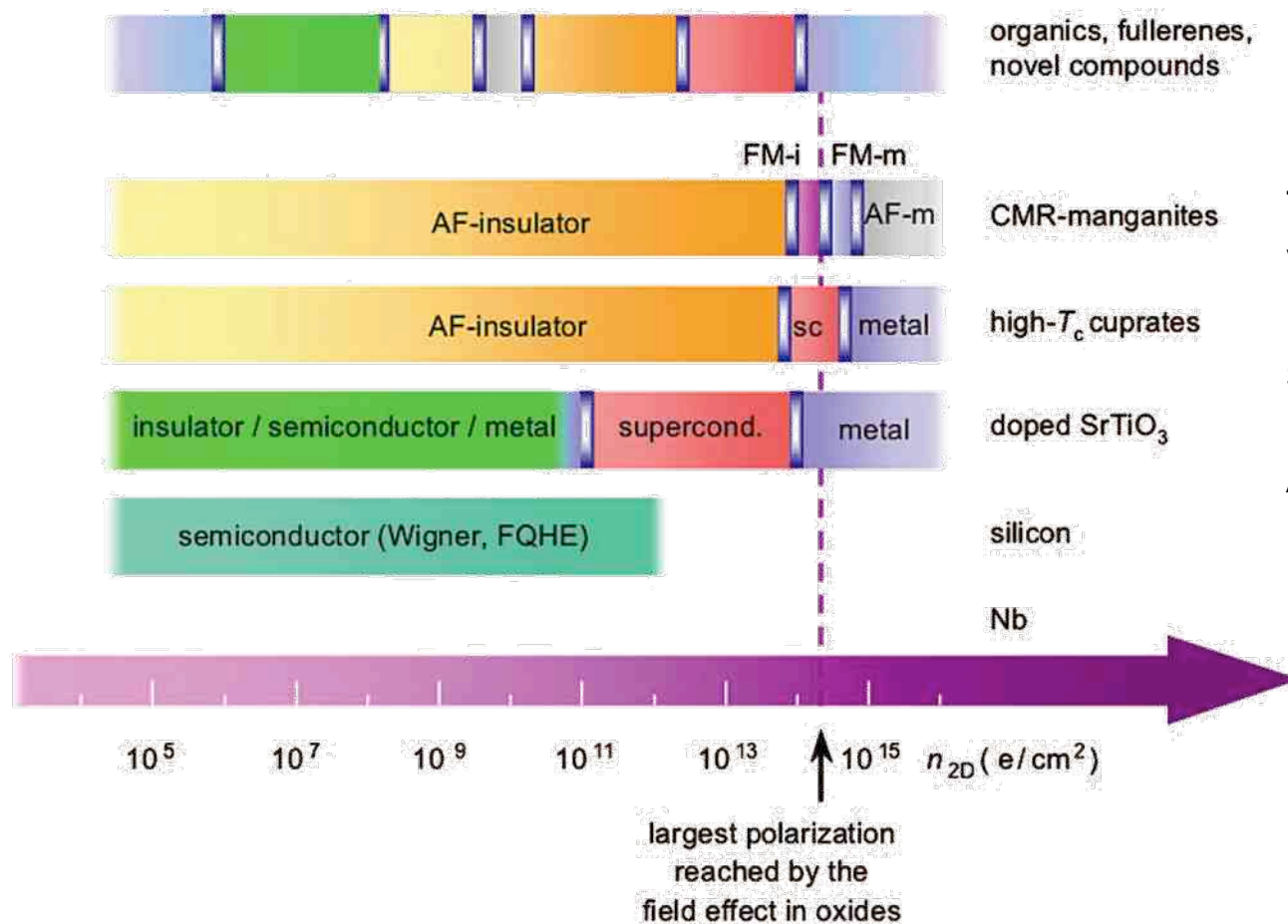
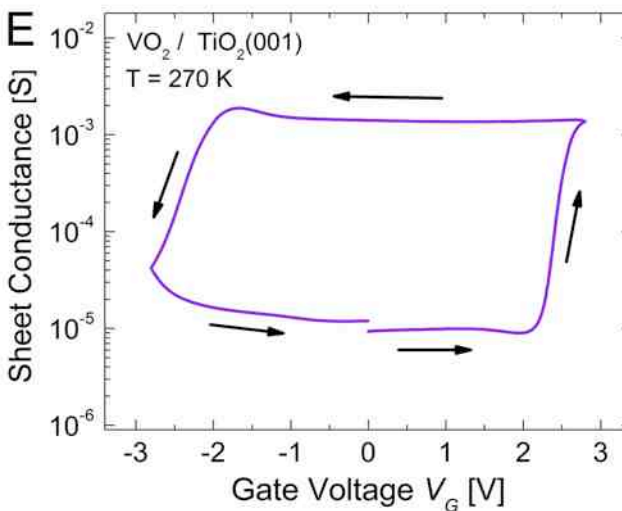
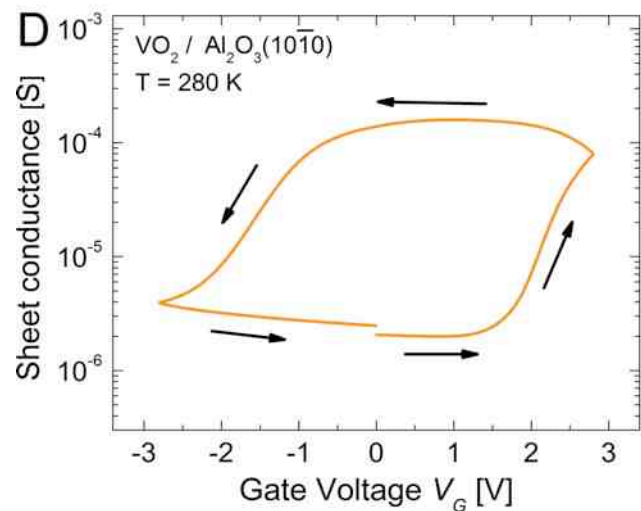
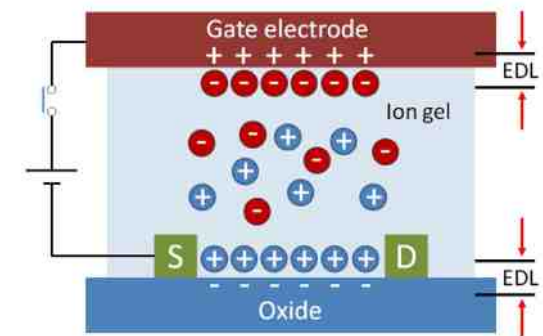
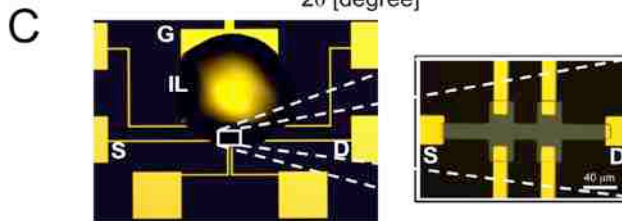
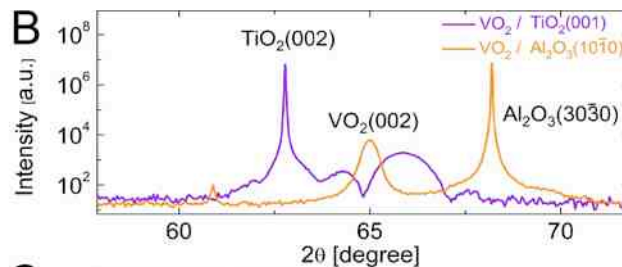
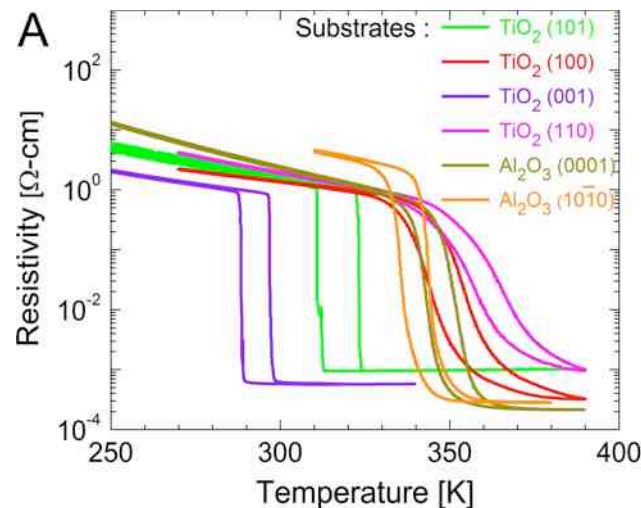


Illustration of the zero temperature behavior of various correlated materials as a function of sheet charge density.

Anh et al., *Rev. Mod. Phys.* (2006)

Ionic liquid gating \rightarrow electric field migration of oxygen



Ionic liquids provide for very high electric field at insulator interfaces
 \rightarrow electrostatic?
 \rightarrow Induces flow of ionic currents associated with migration of oxygen to/from surface

- IL gating effect similar for VO_2 films grown on Al_2O_3 and TiO_2

REPORTS

Suppression of Metal-Insulator Transition in VO_2 by Electric Field–Induced Oxygen Vacancy Formation

Jaewoo Jeong,^{1,2} Nagaphani Aetukuri,^{1,3} Tanja Graf,¹ Thomas D. Schladt,¹ Mahesh G. Samant,¹ Stuart S. P. Parkin^{1*}

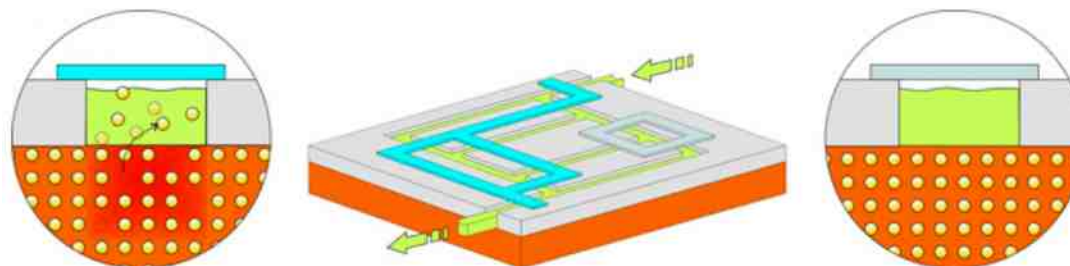
Electrolyte gating with ionic liquids is a powerful tool for inducing novel conducting phases in correlated insulators. An archetypal correlated material is vanadium dioxide (VO_2), which is insulating only at temperatures below a characteristic phase transition temperature. We show that electrolyte gating of epitaxial thin films of VO_2 suppresses the metal-to-insulator transition and stabilizes the metallic phase to temperatures below 5 kelvin, even after the ionic liquid is completely removed. We found that electrolyte gating of VO_2 leads not to electrostatically induced carriers but instead to the electric field–induced creation of oxygen vacancies, with consequent migration of oxygen from the oxide film into the ionic liquid. This mechanism should be taken into account in the interpretation of ionic liquid gating experiments.

Use nanofluidic techniques to deliver ionic liquids
→ “paint” electronic circuits
→ reconfigurable electronics

MARCH 21, 2013, 6:50 PM | 1 Comment

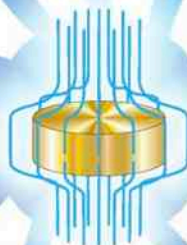
I.B.M. Research Points to Circuits That Mimic the Brain’s Design

By JOHN MARKOFF



A nanofluidic circuit would operate by passing ionic fluid, shown in green, through conduits fabricated on top of a planar oxide surface, shown in orange.

Superconductivity 297K



Synthetic Routes to Room Temperature Superconductivity

October 17-18, 2012

Summer School: October 15-16, 2012

Chairs: Stuart Parkin, IBM Almaden

Claudia Felser, MPI-Dresden

Invited Speakers Include

(Summer School Speakers are highlighted)

Ganapathy Baskaran

Dmitri Basov

Paul Chu

Piers Coleman

Steve Conradson

John Goodenough

Gernot Guntherodt

Hideo Hosono

Hao Tjeng

Bernhard Keimer

Steve Kivelson

Gabriel Kotliar

Brian Maple

Mike Norman

David Pines

Matt Rosseinsky

George Sawatzky

Darrell Schlom

Kyle Shen

Chandra Varma

Harold Weinstock

Qi-Kun Xue



Space is limited!

For more information:

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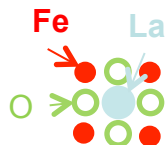
www.regonline.com/SC297K



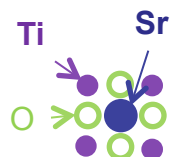
High temperature antiferromagnetic oxides



LaFeO₃
22 unit cells
thick



SrTiO₃



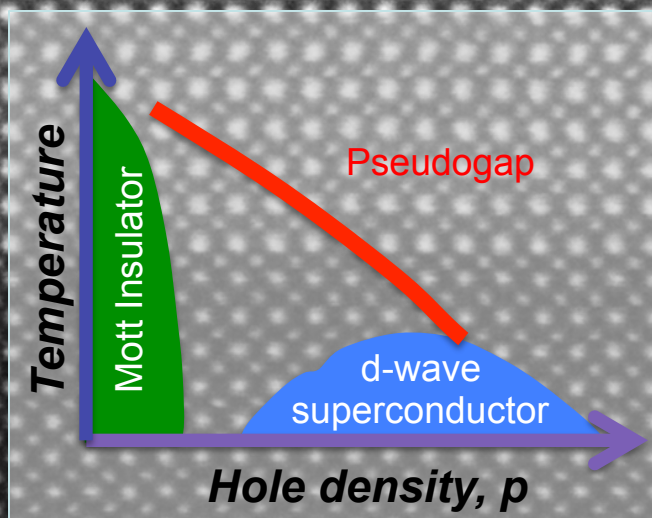
HAADF-STEM
T0986

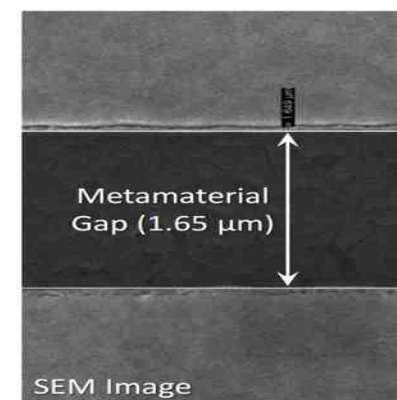
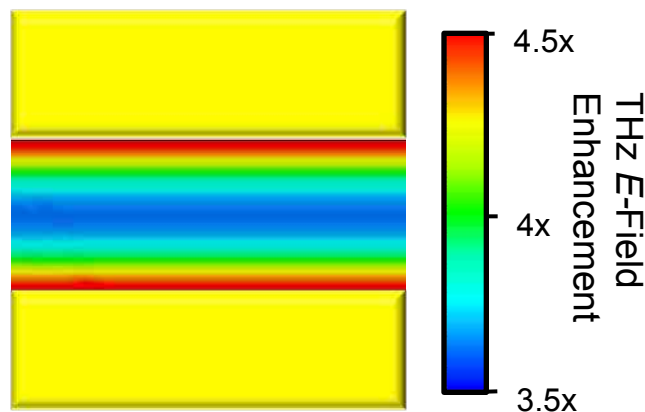
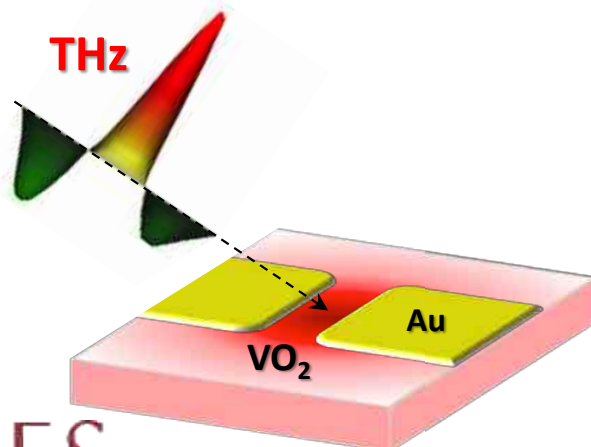
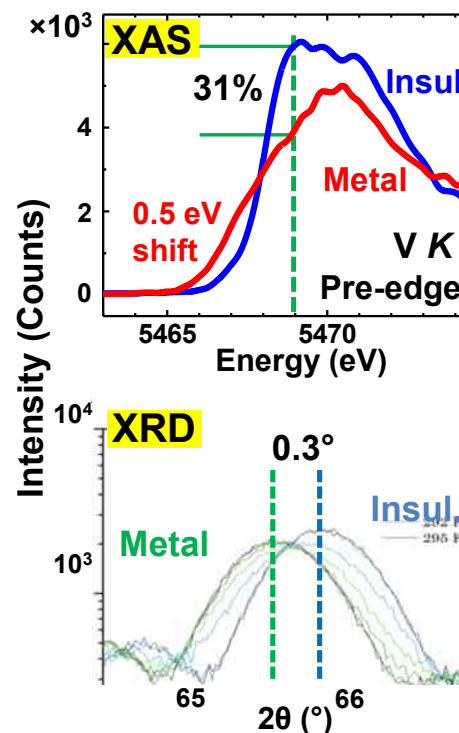
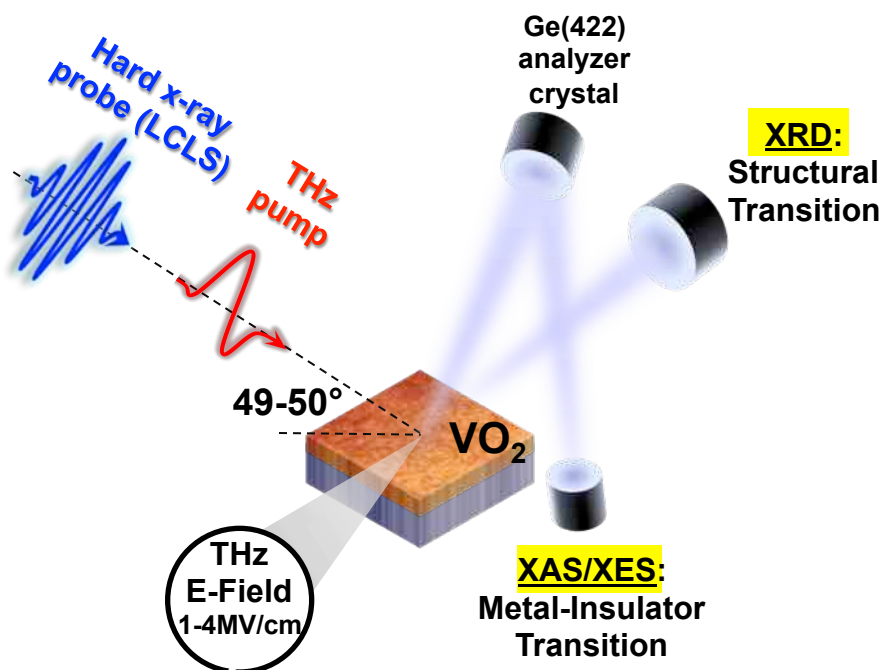
Magnification
= 15×10^6

Atomic column
intensity is based
on the average
atomic number
of the elements
in the column

Atomic Number

La = 57
Sr = 38
Fe = 27
Ti = 22
O = 8





- ❑ Useful materials are complex with a suite of properties that must be met for a given application
 - Often promising materials have unforeseen failure mechanisms
 - ❑ Interfaces between materials often have very different properties from the constituent materials
 - Inorganic/organic interfaces have very interesting functionalities
 - Non-equilibrium materials highly interesting and can be stabilized in thin film form
 - ❑ Transport properties highly dependent on defects e.g. structural, morphological..
 - Generation of spin currents highly useful for sensor, memory, logic and energy harvesting
 - ❑ Systems of devices may behave very differently from individual devices
 - Need systems approach to inverse design/ engineer individual devices
 - ❑ Cognitive devices highly important for future low-energy computing
 - Use of ion currents allows for ultra low energy devices
 - ❑ MGI most useful for evolutionary rather than revolutionary materials?
 - ❑ Need investments in exploratory thin film deposition systems allowing for multiple deposition techniques
- Outcome: computing devices that operate at 1,000,000 x less energy and think differently!

- ❑ During the past century nearly all disruptive advances in science and technology resulted from the discovery of a new material.
- ❑ Major challenges addressing the world today, including sustainability, energy, climate, and health can only be solved by the discovery of new materials or artificially structured nano-materials or composites that address well-defined requirements.
- ❑ Advances in analytics and modeling and simulation suggest that we are at a truly disruptive juncture where computing power combined with advanced modeling and materials expertise and data-mining and data-verification could lead to accelerated computational materials discovery with dramatic world-wide impact.
- ❑ Data-mining of all extant literature to unearth materials properties and characteristics and advanced computational techniques to verify these properties would lead to an unprecedented encyclopedic database of material properties of tremendous value, which would form the basis for computational materials discovery.
- ❑ Challenge encompasses a vast skillset, ranging from the physical to the mathematical and computational sciences.